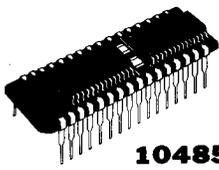


# MH12808TNA-85,-10,-12,-15

1048576-BIT(131072-WORD BY 8-BIT) CMOS STATIC RAM MODULE



## DESCRIPTION

The MH12808TNA is a 1048576-bits CMOS static RAM module organized as 131072-words by 8-bits. It consists of four industry standard 32K x 8 static RAMs and one decoder.

The stand-by current is low enough for a battery backup application. It is mounted a flat package on a 32-pin dual in line package and configured in an industrial standard 128K x 8-bits pin out.

## FEATURES

| Type             | Access time (max) | Power supply current |                |
|------------------|-------------------|----------------------|----------------|
|                  |                   | Active (max)         | Stand-by (max) |
| MH12808 TNA - 85 | 85ns              | 70 mA                | 200 $\mu$ A    |
| MH12808 TNA - 10 | 100ns             |                      |                |
| MH12808 TNA - 12 | 120ns             |                      |                |
| MH12808 TNA - 15 | 150ns             |                      |                |

- JEDEC standard 32-pin 600mil pin out
- Single +5V Power Supply
- No Clocks, No Refresh
- Data-Hold on +2V Power Supply
- Directly TTL Compatible: All Inputs and Outputs
- Three-State Outputs: OR-tie Capability
- Simple Memory Expansion by  $\bar{S}$
- OE Prevents Data Contention in the I/O Bus
- Common Data I/O

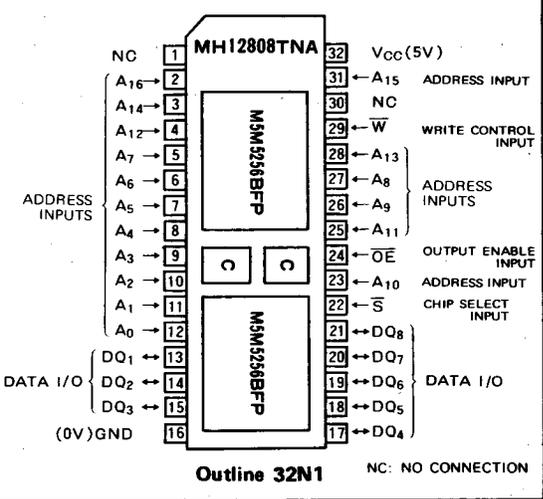
## APPLICATION

Small Capacity Memory Units.

## FUNCTION

The operation mode of the MH12808TNA is determined by a combination of the device control inputs  $\bar{S}$ ,  $\bar{W}$  and  $\bar{OE}$ . Each mode is summarized in the function table. (see next page)

## PIN CONFIGURATION (TOP VIEW)

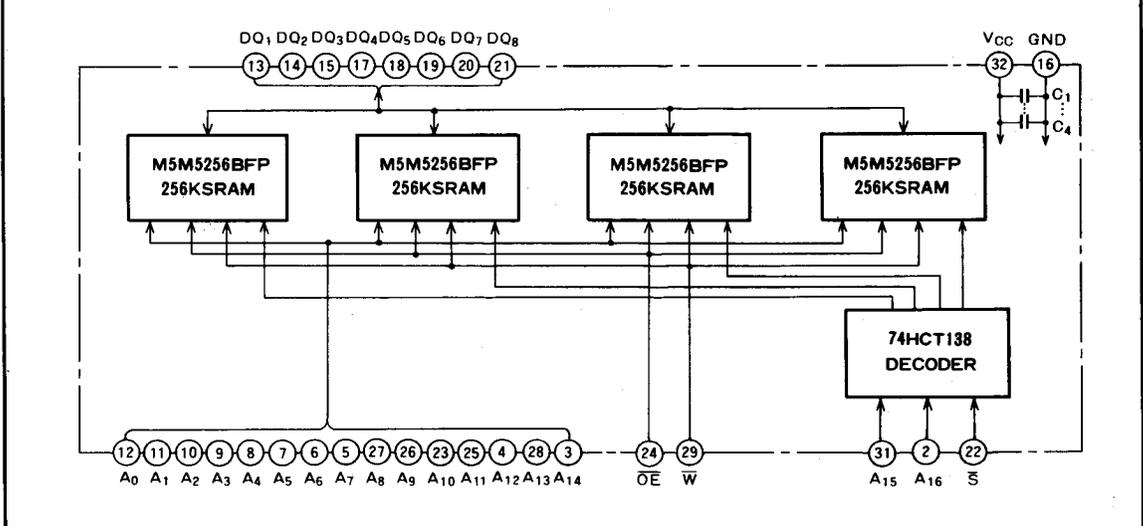


A write cycle is executed whenever the low level  $\bar{W}$  overlaps with the low level  $\bar{S}$ . The address must be set up before the write cycle and must be stable during the entire cycle. The data is latched into a cell on the trailing edge of  $\bar{W}$ ,  $\bar{S}$ , whichever occurs first, requiring the set-up and hold time relative to these edge to be maintained. The output enable  $\bar{OE}$  directly controls the output stage. Setting the  $\bar{OE}$  at a high level, the output stage is in a high-impedance state, and the data bus contention problem in the write cycle is eliminated.

A read cycle is executed by setting  $\bar{W}$  at a high level and  $\bar{OE}$  at a low level while  $\bar{S}$  are in an active state.

When setting  $\bar{S}$  at a high level, the chip is in a non-

## BLOCK DIAGRAM



## 1048576-BIT(131072-WORD BY 8-BIT) CMOS STATIC RAM MODULE

selectable mode in which both reading and writing are disabled. In this mode, the output stage is in a high-impedance state, allowing OR-tie with other chips and memory expansion by  $\bar{S}$ . The power supply current is reduced as low as the stand-by current which is specified as  $I_{CC3}$  or  $I_{CC4}$ , and the memory data can be held +2V power supply, enabling battery back-up operation during power failure or power-down operation in the non-selected mode.

## FUNCTION TABLE

| $\bar{S}$ | $\bar{W}$ | $\bar{OE}$ | Mode          | DQ             | $I_{CC}$ |
|-----------|-----------|------------|---------------|----------------|----------|
| H         | X         | X          | Non selection | High-impedance | Standby  |
| L         | L         | X          | Write         | $D_{IN}$       | Active   |
| L         | H         | L          | Read          | $D_{OUT}$      | Active   |
| L         | H         | H          |               | High-impedance | Active   |

RECOMMENDED OPERATING CONDITIONS ( $T_a = 0 \sim 70^\circ\text{C}$ , unless otherwise noted)

| Symbol   | Parameter          | Limits |     |              | Unit |
|----------|--------------------|--------|-----|--------------|------|
|          |                    | Min    | Typ | Max          |      |
| $V_{CC}$ | Supply voltage     | 4.5    | 5   | 5.5          | V    |
| GND      | Supply voltage     |        | 0   |              | V    |
| $V_{IL}$ | Low input voltage  | -0.3   |     | 0.8          | V    |
| $V_{IH}$ | High input voltage | 2.2    |     | $V_{CC}+0.3$ | V    |

## ABSOLUTE MAXIMUM RATINGS

| Symbol    | Parameter             | Conditions               | Ratings            | Unit             |
|-----------|-----------------------|--------------------------|--------------------|------------------|
| $V_{CC}$  | Supply voltage        | With respect to GND      | -0.3~7             | V                |
| $V_I$     | Input voltage         |                          | -0.3~ $V_{CC}+0.3$ | V                |
| $V_O$     | Output voltage        |                          | 0~ $V_{CC}$        | V                |
| $P_d$     | Power dissipation     | $T_a = 25^\circ\text{C}$ | 700                | mW               |
| $T_{opr}$ | Operating temperature |                          | 0~70               | $^\circ\text{C}$ |
| $T_{stg}$ | Storage temperature   |                          | -40~125            | $^\circ\text{C}$ |

ELECTRICAL CHARACTERISTICS ( $T_a = 0 \sim 70^\circ\text{C}$ ,  $V_{CC} = 5V \pm 10\%$ , unless otherwise noted)

| Symbol    | Parameter                                       | Test conditions   | Limits |     |              | Unit          |
|-----------|---|---|--------|-----|--------------|---------------|
|           |   |   | Min    | Typ | Max          |               |
| $V_{IH}$  | High input voltage                              |   | 2.2    |     | $V_{CC}+0.3$ | V             |
| $V_{IL}$  | Low input voltage                               |   | -0.3   |     | 0.8          | V             |
| $V_{OH}$  | High output voltage                             | $I_{OH} = -1\text{mA}$  | 2.4    |     |              | V             |
| $V_{OL}$  | Low output voltage                              | $I_{OL} = 2\text{mA}$   |        |     | 0.4          | V             |
| $I_I$     | Input current                                   | $V_I = 0 \sim V_{CC}$   |        |     | $\pm 1$      | $\mu\text{A}$ |
| $I_{OZH}$ | High level output current in off-state          | $\bar{S} = V_{IH}$ or $\bar{OE} = V_{IH}$   |        |     | 1            | $\mu\text{A}$ |
| $I_{OZL}$ | Low level output current in off-state           | $V_{I/O} = 0 \sim V_{CC}$   |        |     | -1           | $\mu\text{A}$ |
| $I_{CC1}$ | Active supply current (AC, MOS level)           | $\bar{S} < 0.2$ , $\bar{W} > V_{CC} - 0.3$ output open<br>other input $< 0.2$ or $> V_{CC} - 0.3$<br>Min. cycle         |        | 30  | 65           | mA            |
| $I_{CC2}$ | Active supply current (AC, TTL level)           | $\bar{S} = V_{IL}$ , $\bar{W} = V_{IH}$ output open<br>other input = $V_{IL}$ or $V_{IH}$<br>Min. cycle                 |        | 35  | 70           | mA            |
| $I_{CC3}$ | Stand-by supply current                         | $\bar{S} \geq V_{CC} - 0.2V$<br>$A_{15}$ and $A_{16} \leq 0.2$ or $\geq V_{CC} - 0.2$<br>Other inputs = $0 \sim V_{CC}$ |        |     | 200          | $\mu\text{A}$ |
| $I_{CC4}$ | Stand-by supply current                         | $\bar{S} = V_{IH}$ , Other inputs = $0 \sim V_{CC}$   |        |     | 3            | mA            |
| $C_i$     | Input capacitance ( $T_a = 25^\circ\text{C}$ )  | $V_I = \text{GND}$ , $V_i = 25\text{mVrms}$ , $f = 1\text{MHz}$   |        |     | 30           | pF            |
| $C_o$     | Output capacitance ( $T_a = 25^\circ\text{C}$ ) | $V_O = \text{GND}$ , $V_O = 25\text{mVrms}$ , $f = 1\text{MHz}$   |        |     | 30           | pF            |

Note 1: Direction for current flowing into IC is indicated as positive (no mark)

2: Typical value is  $V_{CC} = 5V$ ,  $T_a = 25^\circ\text{C}$

**MH12808TNA-85, -10, -12, -15****1048576-BIT(131072-WORD BY 8-BIT)CMOS STATIC RAM MODULE****SWITCHING CHARACTERISTICS** ( $T_a=0\sim 70^\circ\text{C}$ ,  $V_{CC}=5V\pm 10\%$ , unless otherwise noted)**Read cycle**

| Symbol        | Parameter                                 | Limits        |     |     |               |     |     |               |     |     |               |     |     | Unit |
|---------------|---|---------------|-----|-----|---------------|-----|-----|---------------|-----|-----|---------------|-----|-----|------|
|               |   | MH12808TNA-85 |     |     | MH12808TNA-10 |     |     | MH12808TNA-12 |     |     | MH12808TNA-15 |     |     |      |
|               |   | Min           | Typ | Max |      |
| $t_{CR}$      | Read cycle time                           | 85            |     |     | 100           |     |     | 120           |     |     | 150           |     |     | ns   |
| $t_{a(A)}$    | Address access time                       |               |     | 85  |               |     | 100 |               |     | 120 |               |     | 150 | ns   |
| $t_{a(S)}$    | Chip select access time                   |               |     | 85  |               |     | 100 |               |     | 120 |               |     | 150 | ns   |
| $t_{a(OE)}$   | Output enable access time                 |               |     | 45  |               |     | 50  |               |     | 60  |               |     | 75  | ns   |
| $t_{dis(S)}$  | Output disable time after $\bar{S}$ high  |               |     | 30  |               |     | 35  |               |     | 40  |               |     | 45  | ns   |
| $t_{dis(OE)}$ | Output disable time after $\bar{OE}$ high |               |     | 30  |               |     | 35  |               |     | 40  |               |     | 45  | ns   |
| $t_{en(S)}$   | Output enable time after $\bar{S}$ low    | 10            |     |     | 10            |     |     | 10            |     |     | 10            |     |     | ns   |
| $t_{en(OE)}$  | Output enable time after $\bar{OE}$ low   | 10            |     |     | 10            |     |     | 10            |     |     | 10            |     |     | ns   |
| $t_V(A)$      | Data valid time after address change      | 20            |     |     | 20            |     |     | 20            |     |     | 20            |     |     | ns   |

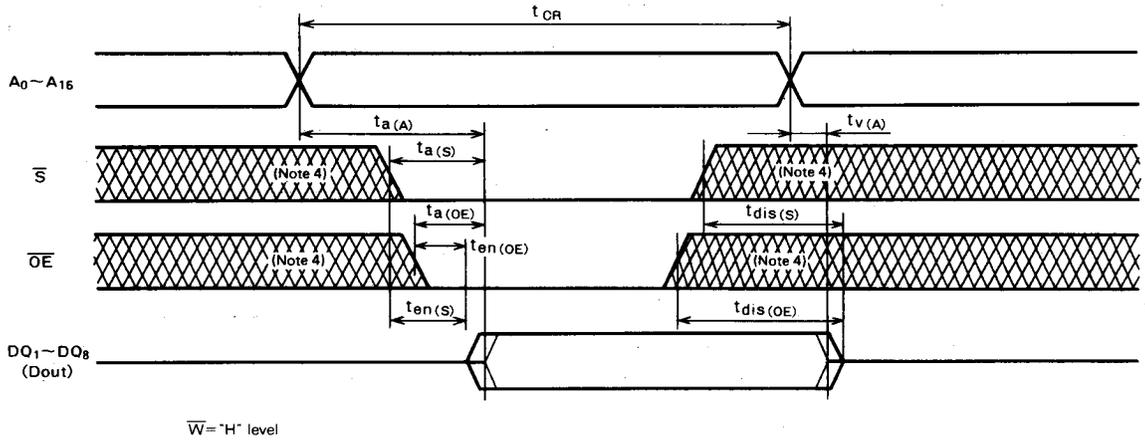
**TIMING REQUIREMENTS** ( $T_a=0\sim 70^\circ\text{C}$ ,  $V_{CC}=5V\pm 10\%$ , unless otherwise noted)**Write cycle**

| Symbol               | Parameter  | Limits        |     |     |               |     |     |               |     |     |               |     |     | Unit |
|----------------------|--|---------------|-----|-----|---------------|-----|-----|---------------|-----|-----|---------------|-----|-----|------|
|                      |  | MH12808TNA-85 |     |     | MH12808TNA-10 |     |     | MH12808TNA-12 |     |     | MH12808TNA-15 |     |     |      |
|                      |  | Min           | Typ | Max |      |
| $t_{CW}$             | Write cycle time                                   | 85            |     |     | 100           |     |     | 120           |     |     | 150           |     |     | ns   |
| $t_{W(W)}$           | Write pulse width                                  | 60            |     |     | 60            |     |     | 70            |     |     | 80            |     |     | ns   |
| $t_{su(A)}$          | Address set up time                                | 0             |     |     | 0             |     |     | 0             |     |     | 0             |     |     | ns   |
| $t_{su(A-\bar{W}H)}$ | Address set up time with respect to $\bar{W}$ high | 75            |     |     | 80            |     |     | 85            |     |     | 90            |     |     | ns   |
| $t_{su(S)}$          | Chip select set up time                            | 75            |     |     | 80            |     |     | 85            |     |     | 90            |     |     | ns   |
| $t_{su(D)}$          | Data set up time                                   | 35            |     |     | 35            |     |     | 40            |     |     | 50            |     |     | ns   |
| $t_h(D)$             | Data hold time                                     | 0             |     |     | 0             |     |     | 0             |     |     | 0             |     |     | ns   |
| $t_{rec(W)}$         | Write recovery time                                | 0             |     |     | 0             |     |     | 0             |     |     | 0             |     |     | ns   |
| $t_{dis(W)}$         | Output disable time after $\bar{W}$ low            |               |     | 30  |               |     | 35  |               |     | 40  |               |     | 45  | ns   |
| $t_{dis(OE)}$        | Output disable time after $\bar{OE}$ high          |               |     | 30  |               |     | 35  |               |     | 40  |               |     | 45  | ns   |
| $t_{en(W)}$          | Output enable time after $\bar{W}$ high            | 10            |     |     | 10            |     |     | 10            |     |     | 10            |     |     | ns   |
| $t_{en(OE)}$         | Output enable time after $\bar{OE}$ low            | 10            |     |     | 10            |     |     | 10            |     |     | 10            |     |     | ns   |

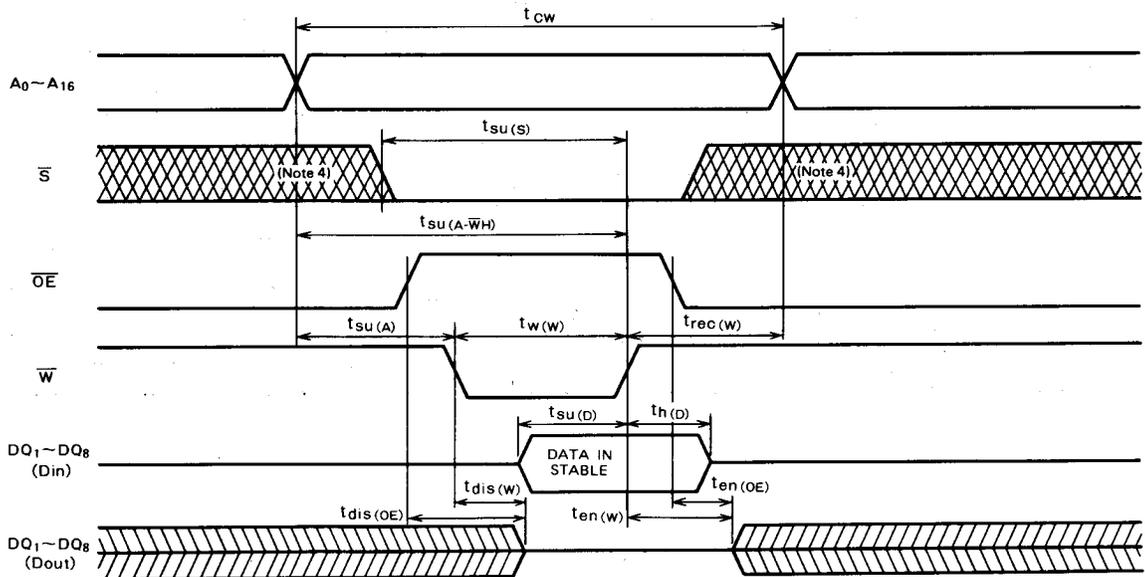
1048576-BIT(131072-WORD BY 8-BIT)CMOS STATIC RAM MODULE

TIMING DIAGRAM

Read cycle



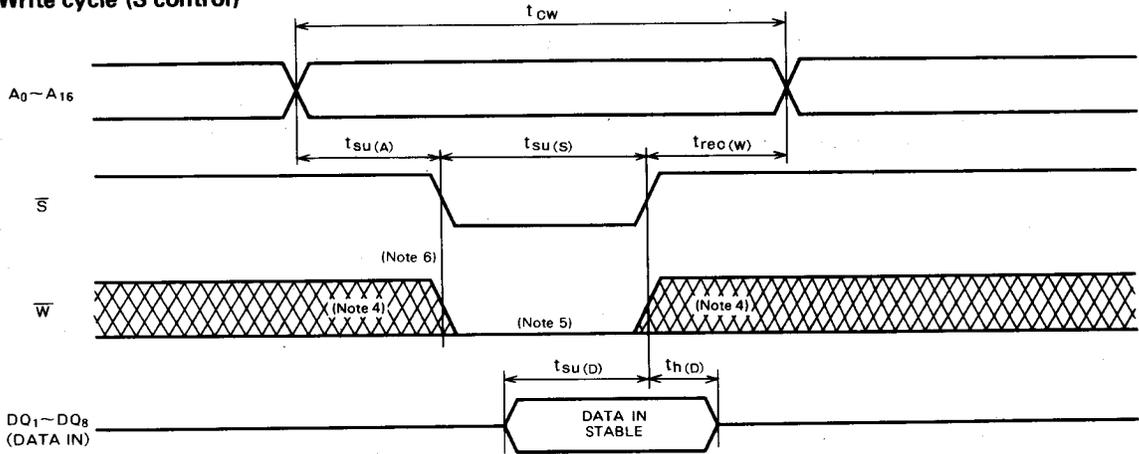
Write cycle ( $\overline{W}$  control)



# MH12808TNA-85, -10, -12, -15

## 1048576-BIT(131072-WORD BY 8-BIT)CMOS STATIC RAM MODULE

### Write cycle ( $\bar{S}$ control)



- Note 3: Test condition  
 Input pulse level: 0.6 ~ 2.4V  
 Input pulse rise fall time: 10ns  
 Load: 1 TTL.  $C_L = 100pF$   
 Conditions of assessment: 1.5V
- 4: Hatching indicates the state is don't care.  
 5: Writing is executed in overlap of  $\bar{S}$  and  $\bar{W}$  low.  
 6: If  $\bar{W}$  goes low simultaneously with or prior to  $\bar{S}$ , the output remains in the high-impedance state.  
 7: Don't active inverted phase signal externally when DQ pin is in output mode.

### POWER DOWN CHARACTERISTICS

#### ELECTRICAL CHARACTERISTICS ( $T_a = 0 \sim 70^\circ C$ , unless otherwise noted)

| Symbol         | Parameter                   | Test conditions   | Limits |              |     | Unit    |
|----------------|-----------------------------|---|--------|--------------|-----|---------|
|                |                             |   | Min    | Typ          | Max |         |
| $V_{CC(PD)}$   | Power down supply voltage   |   | 2      |              |     | V       |
| $V_I(\bar{S})$ | Chip select input $\bar{S}$ | $2.2V \leq V_{CC(PD)}$  | 2.2    |              |     | V       |
|                |                             | $2V \leq V_{CC(PD)} \leq 2.2V$  |        | $V_{CC(PD)}$ |     | V       |
| $I_{CC(PD)}$   | Power down supply current   | $V_{CC} = 3V, A_{15} \text{ and } A_{16} < 0.2 \text{ or } > V_{CC} - 0.2, \text{ Other inputs } = 0 \sim V_{CC}$ |        |              | 100 | $\mu A$ |

#### TIMING REQUIREMENTS ( $T_a = 0 \sim 70^\circ C$ , unless otherwise noted)

| Symbol        | Parameter                | Test conditions | Limits   |     |     | Unit |
|---------------|--------------------------|-----------------|----------|-----|-----|------|
|               |                          |                 | Min      | Typ | Max |      |
| $t_{su(PD)}$  | Power down setup time    |                 | 0        |     |     | ns   |
| $t_{rec(PD)}$ | Power down recovery time |                 | $t_{CR}$ |     |     | ns   |

### POWER DOWN CHARACTERISTICS

